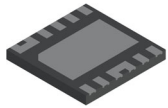
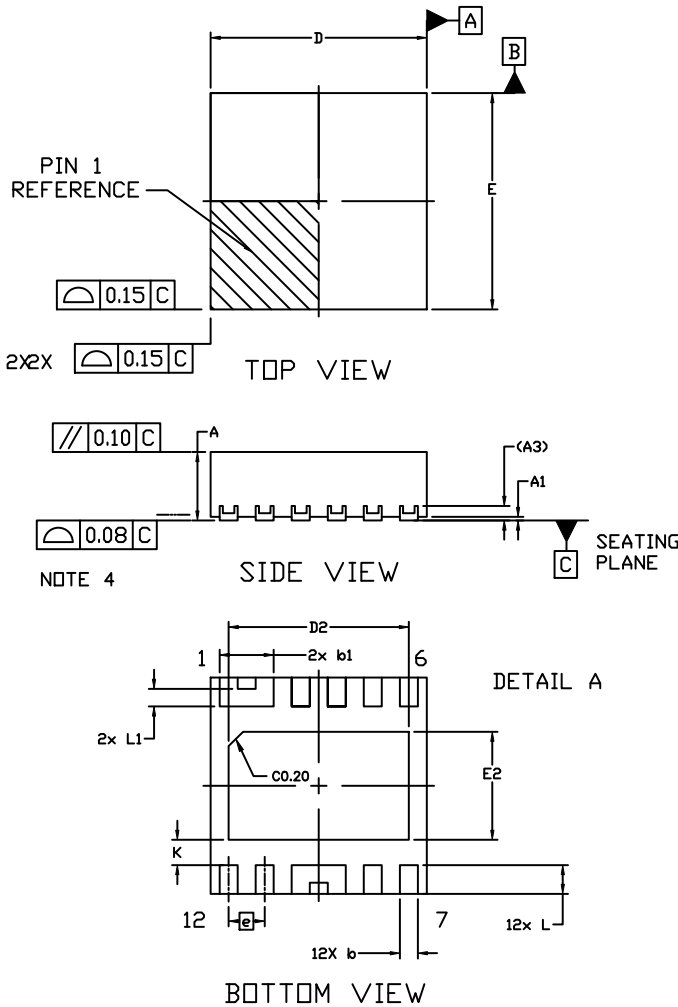


MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



DFN12 3x3, 0.5P
CASE 506FD
ISSUE O

DATE 28 JAN 2022

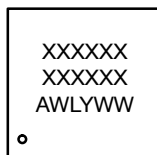


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 MM FROM THE TERMINAL TIP.
4. COPLANARITY APPLIES TO THE EXPOSED PADS AS WELL AS THE TERMINALS.
5. POSITIONAL TOLERANCE APPLIES TO ALL THREE EXPOSED PADS IN BOTH X AND Y AXIS.

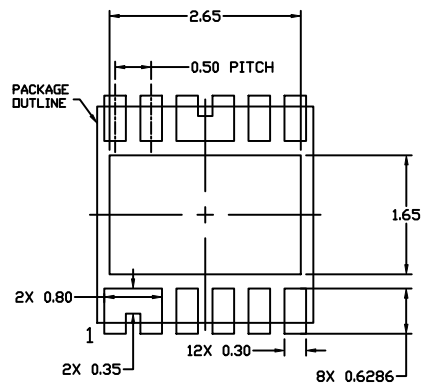
DIM	MILLIMETERS		
	MIN.	NDM.	MAX.
A	0.90	0.95	1.00
A1	---	---	0.05
A3	0.20 REF		
b	0.20	0.25	0.30
b1	0.70	0.75	0.80
D	2.90	3.00	3.10
D2	2.40	2.50	2.60
E	2.90	3.00	3.10
E2	1.40	1.50	1.60
e	0.50 BSC		
K	0.35 REF		
L	0.30	0.40	0.50
L1	0.25 REF		

GENERIC MARKING DIAGRAM*



XXXX = Specific Device Code
A = Assembly Location
WL = Wafer Lot
Y = Year
WW = Work Week

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "μ", may or may not be present. Some products may not follow the Generic Marking.



RECOMMENDED MOUNTING FOOTPRINT

* For additional information on our Pb-free strategy and soldering details, please download the DN Semiconductor Soldering and Mounting Techniques Reference Manual, SLDERRM/D.

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DESCRIPTION:	DFN12 3x3, 0.5P	PAGE 1 OF 1

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